

AMENDMENTS TO THE CLAIMS

1. (Original) A copper(I) formate complex of the formula $L_n\text{Cu}(\text{HCOO}) \cdot x \text{HCOOH}$, where x is from 0 to 10, n is 1, 2, 3 or 4 and the n ligands L, independently of one another, are each one of the following ligands:

- a phosphane of the formula $\text{R}^1\text{R}^2\text{R}^3\text{P}$;
- a phosphite of the formula $(\text{R}^1\text{O})(\text{R}^2\text{O})(\text{R}^3\text{O})\text{P}$;
- an isocyanide of the formula $\text{R}^1\text{-NC}$;
- an alkene of the formula $\text{R}^1\text{R}^2\text{C}=\text{CR}^3\text{R}^4$; or
- an alkyne of the formula $\text{R}^1\text{C}\equiv\text{CR}^2$;

where R^1 , R^2 , R^3 and R^4 , independently of one another, are hydrogen, a linear or branched, optionally partly or completely fluorinated alkyl, aminoalkyl, alkoxyalkyl, hydroxyalkyl, phosphinoalkyl or aryl radical of one to 20 carbon atoms;

with the exception of triphenylphosphinocopper(I) formate and 1,1,1-tris(diphenylphosphinomethyl)ethanecopper(I) formate.

2. (Currently Amended) The $[[A]]$ copper(I) formate complex according to claim 1, wherein n is 2 or 3.

3. (Currently Amended) The $[[A]]$ copper(I) formate complex according to claim 1 ~~or 2~~, wherein L is selected from the group consisting of trimethylphosphine, triethylphosphine, triisopropylphosphine, tri-n-butylphosphine, triisobutylphosphine, tricyclopentylphosphine, trimethoxyphosphine, triethoxyphosphine, triisopropoxyphosphine, tri(2,2,2-trifluoroethoxy)phosphine, isopropyl isocyanide, n-butyl isocyanide, tert-butyl isocyanide and cyclohexyl isocyanide.

4. (Currently Amended) The $[[A]]$ copper(I) formate complex according to claim 3, wherein L is tri-n-butylphosphine.

5. (Currently Amended) The ~~[[A]]~~ copper(I) formate complex according to claim 4, wherein x is 1.

6. (Currently Amended) A process for the preparation of a copper(I) formate complex defined in ~~any of claims 1 to 5~~ claim 1 by reacting copper(I) formate with ligand L and optionally formic acid.

7. (Currently Amended) The ~~[[A]]~~ process according to claim 6, wherein the copper(I) formate is obtained in a first step from copper(II) formate, metallic copper and formic acid and is not isolated before addition of the ligand L.

8. (Currently Amended) A process for the preparation of a copper(I) formate complex defined in ~~any of claims 1 to 5~~ claim 1 by reacting a copper(I) halide complex of the formula $L_nCu(I)X$, where X is a halide and L and n have the meanings defined in claim 1, with formic acid and then with a base.

9. (Currently Amended) A process for depositing metallic copper on a substrate by application of a copper(I) formate complex defined in ~~any of claims 1 to 5~~ claim 1 to the substrate and thermal decomposition of the copper(I) formate complex at a temperature of at least 80°C.

10. (Currently Amended) The ~~[[A]]~~ process according to claim 9, wherein the copper(I) formate complex is deposited from the gas phase and simultaneously decomposed.

11. (Currently Amended) The ~~A~~ process according to claim 9, wherein the substrate is sprayed with a solution of the copper(I) formate complex and the latter is simultaneously or subsequently decomposed.

12. (Currently Amended) The [[A]]process according to claim 9, wherein a solution of the copper(I) formate complex is applied to a rotating substrate and the copper(I) formate complex is simultaneously or subsequently decomposed.

DISCUSSION OF AMENDMENTS

Claim 1 is original.

Claims 2-12 are currently amended.

Upon entry of the amendment, claims 1-12 will be active.

The claims were amended to remove multiple dependencies and to clarify claim language.

No new matter has been added by the amendment.